



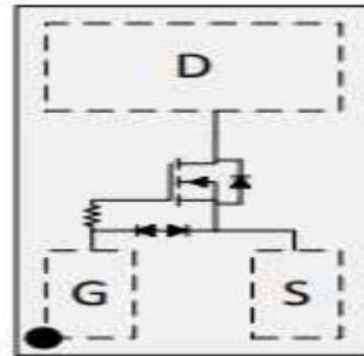
SSC8122GN5

N-Channel Enhancement Mode MOSFET with ESD Protection

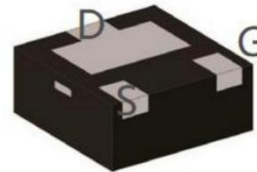
➤ Features

VDS	VGS	RDSON Typ.	ID	ESD
20V	±8V	200mR@4V5	2A	1K
		290mR@2V5		
		450mR@1V8		

➤ Pin configuration



Top view



DFN1616

➤ Description

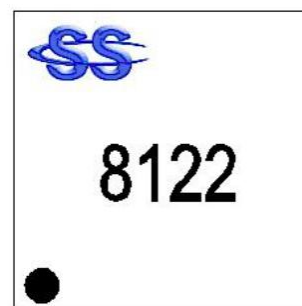
This device is a N-Channel enhancement mode MOSFET which is produced with high cell density and DMOS trench technology. This device particularly suits low voltage applications, especially for battery powered circuits, the tiny and thin outline saves PCB consumption.

➤ Applications

- Replace Digital Transistor
- Battery Operated Systems
- Power Supply Converter Circuits
- Load/Power Switching cell Phones

➤ Ordering Information

Device	Package	Shipping
SSC8122GN5	DFN1616	3000/Reel



Marking



➤ **Absolute Maximum Ratings**($T_A=25^{\circ}\text{C}$ unless otherwise noted)

Symbol	Parameter	Ratings	Unit
V_{DSS}	Drain-to-Source Voltage	20	V
V_{GSS}	Gate-to-Source Voltage	± 8	V
I_D	Continuous Drain Current ^a	2	A
I_{DM}	Pulsed Drain Current ^b	6	A
P_D	Power Dissipation ^c	2	W
T_J	Operation junction temperature	-55 to 150	$^{\circ}\text{C}$
T_{STG}	Storage temperature range	-55 to 150	$^{\circ}\text{C}$

➤ **Thermal Resistance Ratings**($T_A=25^{\circ}\text{C}$ unless otherwise noted)

Symbol	Parameter	Maximum	Unit
$R_{\theta JA}$	Junction-to-Ambient Thermal Resistance ^a	60	$^{\circ}\text{C}/\text{W}$

Note:

- The value of $R_{\theta JA}$ is measured with the device mounted on 1 in² FR-4 board with 2oz.copper,in a still air environment with $T_A=25^{\circ}\text{C}$.The value in any given application depends on the user is specific board design. The current rating is based on the $t \leq 10\text{s}$ thermal resistance rating.
- Repetitive rating, pulse width limited by junction temperature.
- The power dissipation P_D is based on $T_J(\text{MAX})=150^{\circ}\text{C}$, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.

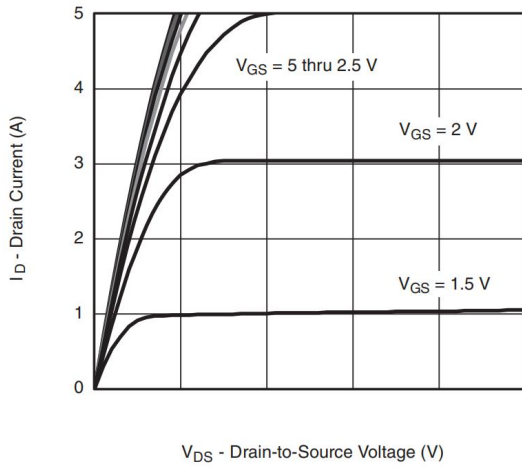


➤ **Electronics Characteristics**($T_A=25^{\circ}\text{C}$ unless otherwise noted)

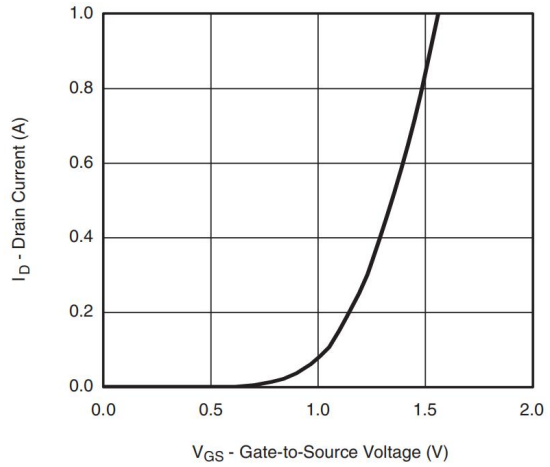
Symbol	Parameter	Test Conditions	Min	Typ.	Max	Unit
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	20			V
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	0.5	0.8	1	V
$R_{DS(on)}$	Drain-Source On-Resistance	$V_{GS}=4.5V, I_D=0.5A$		200	350	mR
		$V_{GS}=2.5V, I_D=0.3A$		290	400	
		$V_{GS}=1.8V, I_D=0.1A$		450	800	
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=20V, V_{GS}=0V$			1	μA
I_{GSS}	Gate-Source leak current	$V_{GS}=\pm 8V, V_{DS}=0V$			± 10	μA
G_{FS}	Transconductance	$V_{DS}=5V, I_D=2A$		2		S
V_{SD}	Forward Voltage	$V_{GS}=0V, I_S=2.2A$		0.7	1.3	V
C_{iss}	Input Capacitance	$V_{DS}=10V, V_{GS}=0V, f=1MHz$		50		pF
C_{oss}	Output Capacitance			12		
C_{rss}	Reverse Capacitance			7		
$T_{D(ON)}$	Turn-on delay time	$V_{GS}=4.5V,$ $V_{DS}=10V, R_L=5R$ $R_G=3R$		2		ns
T_r	Rise time			4		
$T_{D(OFF)}$	Turn-off delay time			10		
T_f	Fall time			8		
Q_g	Total Gate charge	$V_{GS}=4.5V, V_{DS}=10V$ $I_D=2A$		0.8		nC
Q_{gs}	Gate Source charge			0.1		
Q_{gd}	Gate Drain charge			0.2		



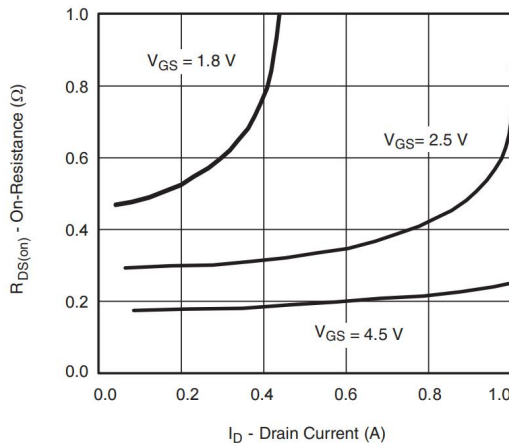
➤ **Typical Characteristics** ($T_A=25^\circ\text{C}$ unless otherwise noted)



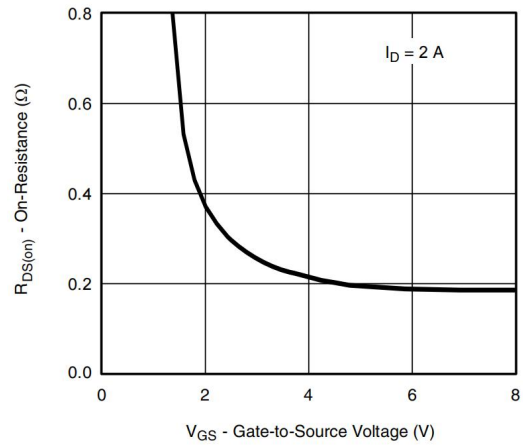
Output Characteristics



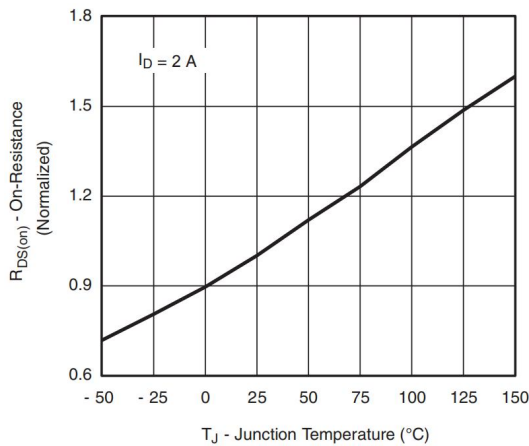
Transfer Characteristics



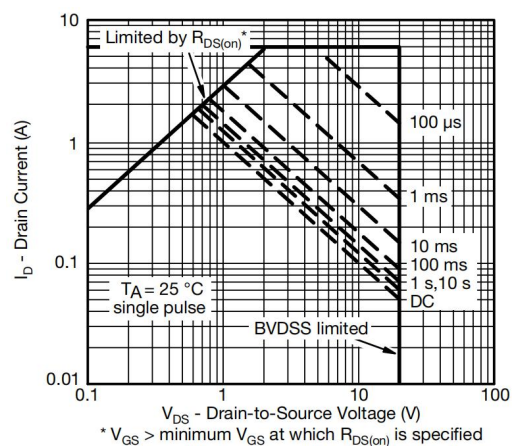
On-Resistance vs. Drain Current and Gate Voltage



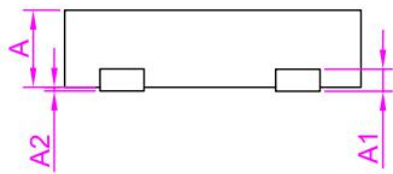
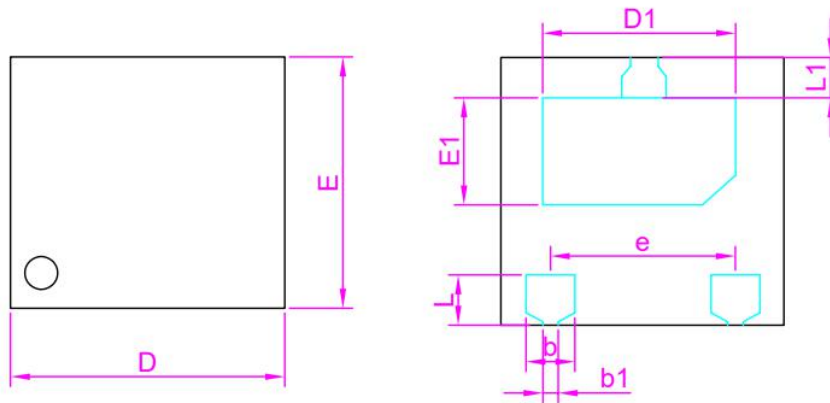
On-Resistance vs. Gate-to-Source Voltage



On-Resistance vs. Junction Temperature



Safe Operating Area, Junction-to-Case

➤ Package Information


COMMON DIMENSION (MM)			
PKG	DFN1616-3L		
REF.	MIN.	NOM.	MAX.
A	0.50	0.55	0.60
D	1.55	1.60	1.65
E	1.55	1.60	1.65
b	0.35	0.40	0.45
L	0.35	0.40	0.45
e	1.00BSC		
D1	1.15	1.20	1.25
E1	0.50	0.55	0.65
b1	0.15	0.20	0.25
L1	0.20	0.25	0.30
A1	0.15BSC		
A2	0.00	0.025	0.05



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